



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-08-05
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD5N95K5	XNDP*VJLDB5F	A	Z8GA	2016-08-05
Amount		UoM	Unit type	ST ECOPACK Grade
330.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	gull wing	
Comment	Package: TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	XNDP*V/LDBSF					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.998	mg	supplier	die	Silicon (Si)	7440-21-3		4.381	mg	876551	13276
				supplier	metallization	Aluminium (Al)	7429-90-5		0.504	mg	100840	1527
				supplier	Passivation	Silicon Nitride	12033-89-5		0.027	mg	5402	82
				supplier	Passivation	Silicon Oxide	7631-86-9		0.043	mg	8603	130
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	400	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.030	mg	6002	91
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.011	mg	2201	33
Leadframe	Copper & its alloys	180.956	mg	supplier	alloy	Copper (Cu)	7440-50-8		179.518	mg	992053	543994
				supplier	alloy	Iron (Fe)	7439-89-6		0.083	mg	459	251
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.151	mg	834	458
				supplier	metallization	Nickel (Ni)	7440-02-0		1.197	mg	6615	3627
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	39	21
Soft solder	Solder	4.223	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.032	mg	954771	12218
				supplier	solder	Silver (Ag)	7440-22-4		0.106	mg	25101	321
				supplier	solder	Tin (Sn)	7440-31-5		0.085	mg	20128	258
Bonding wire	Other inorganic materials	0.253	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.253	mg	1000000	767
				supplier	mold compound	Epoxy Resin	25068-38-6		4.152	mg	30007	12582
Encapsulation	Other inorganic materials	138.369	mg	supplier	mold compound	2,2'-((3,3',5,5'-tetramethyl-(1,1'-biphenyl)-4,4'	EC 413-900-7		5.536	mg	40009	16776
				supplier	mold compound	phenol resin	29690-82-2		6.917	mg	49990	20961
				supplier	mold compound	Silica, vitreous	60676-86-0		121.073	mg	875001	366888
				supplier	mold compound	Carbon black	1333-86-4		0.691	mg	4994	2094
Connections coating	Solder	1.201	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.201	mg	1000000	3639